

87654321

UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.
NOTES PRECEDED BY AN UNMARKED "□" ARE NOT APPLICABLE.

1. APPLICATION DESIGN MANUFACTURING AND INSPECTION DOCUMENTS.
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.
IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.

2. HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE +/- .003.

3. REGISTRATION TOLERANCE: ARTWORK +/- .002
ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.

4. MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.
FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.

5. PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
MATERIAL: MULTI-LAYER POLYCLAD 370HR (SEE DETAIL A)
NUMBER OF FINISHED LAYERS: 4 BOARD THICKNESS: .062 +/- .10%

6. MANUFACTURE'S LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF BOARD.

7. SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT). COLOR=RED (0.001 TO 0.002" THICK OVER METAL).

8. SILKSCREEN BOTH SIDES. USING WHITE NPI LEADFREE.
REGISTRATION TOLERANCE TO BE +/- .005. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.

9. P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.

10. BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH
MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.

11. BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

12. ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.

13. TOP LAYER 18.0MIL TRACES TO BE 50 OHM CONTROLLED IMPEDANCE +/-10% WITH REFERENCE TO LAYER 2.

14. MINIMUM COPPER CONDUCTOR WIDTH IS: 6.5MIL.
MINIMUM COPPER SPACING IS: 5MIL.

15. SMOBC/IMMERSION GOLD: 3-8 uIN OVER 100-200 NICKEL.

16. NO CHANGES TO THE ARTWORK ARE PERMITTED WITHOUT WRITTEN AUTHORIZATION.

17. ALL THRU HOLE VIAS TO BE PLUGGED WITH NON-CONDUCTIVE EPOXY MATERIAL.
PLUGGED VIAS SHALL BE COPLANAR WITH SURFACE FINISH.

18. GROUND ETCH ON LAYERS TO BOARD EDGE IS INTENTIONAL.
DO NOT PULL BACK.

19. BOARD TO BE PANELIZED FOR ASSEMBLY PURPOSE.

20. PWB MUST BE RoHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY,
MAX REFLOW OF 260 DEGREES C (6 PASSES).

REVISIONS

ZONE	LTR	DESCRIPTION	DATE	APPROVED
------	-----	-------------	------	----------

3.000

2.850

.150

.150

3.150

3.300

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	PLATED	QTY
•	8.0	PLATED	1553
•	10.0	PLATED	315
•	12.0	PLATED	21
•	38.0	PLATED	10
•	40.0	PLATED	26
•	53.0	PLATED	5
•	62.0	PLATED	4
•	125.0	PLATED	4
•	39.0	NON-PLATED	2

SEE NOTE 17
SEE NOTE 17

LAYER 1

TOP

Copper Foil .38oz / Plate to .5oz min Layer 1

LAYER 2

POLYCLAD 370HR

Pre-preg 0.011"

LAYER 3

Core 0.033" 1.0oz / 1.0oz Layer 2 & 3

Pre-preg 0.011"

LAYER 4

BOTTOM

Copper Foil .38oz / Plate to .5oz min Layer 4

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS DECIMALS ANGLES
+/- .XX +/- .01 +/-
.XXX +/- .005 +/-

CONTRACT NO.

APPROVALS

DATE

DRAWN JV SMITH 06-31-11

CHECKED P HANISH 06-31-11

MATERIAL

SEE NOTE 5

FINISH

SEE NOTE 7, 8, 9

DO NOT SCALE DRAWING

TEXAS INSTRUMENTS INC.

FABRICATION DRAWING

TRF3765

SIZE

CODE

IDENT NO.

DRAWING NO.

REV.

D

SCALE

NONE

SHEET 1 OF 1